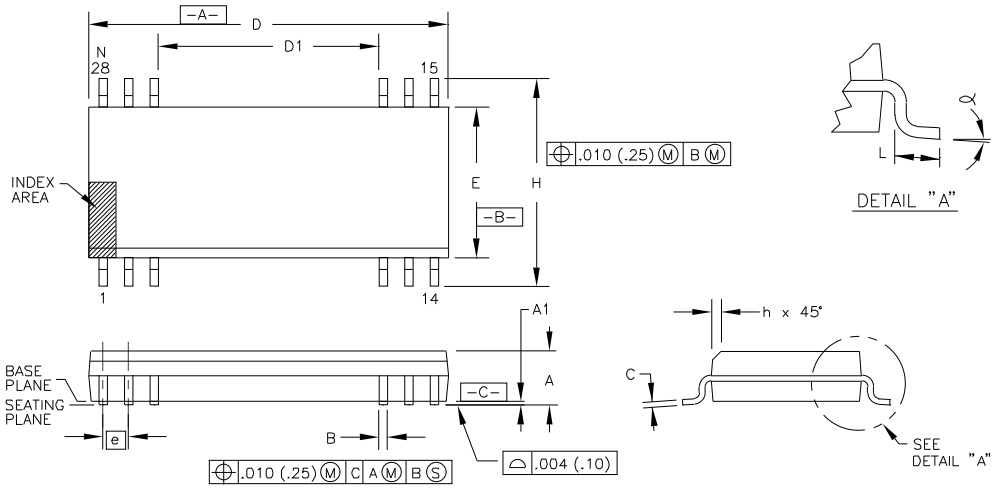
Package Number 217-2 - 28-Lead SOIC, ISO Package



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.0926	.1043	2.35	2.65	
A1	.004	.0118	0.10	0.30	
B	.013	.020	0.33	0.51	7
C	.0091	.0125	0.23	0.32	
D	.6969	.7125	17.70	18.10	2
D1	.426	.441	10.82	11.20	
E	.2914	.2992	7.42	7.60	3
e	.050 BASIC		1.27 BASIC		
H	.394	.419	10.01	10.65	
h	.010	.0295	0.25	0.75	4
L	.016	.050	0.41	1.27	5
N	12		12		6
∝	0°	8°	0°	8°	

DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M–1982.
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
3. DIMENSION E DOES NOT INCLUDE INTER–LEAD FLASH OR PROTRUSIONS. INTER–LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
4. THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS–HATCHED AREA.
5. L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
6. N IS THE NUMBER OF TERMINAL POSITIONS.
7. THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
8. LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.

PACKAGE NUMBER: ZZ217–2	REV.: D
JEDEC NUMBER: MS–013–AE WITH THE EXCEPTION OF "N"	

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PACKAGE DRAWING

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